

**MULTI-STEP POLISH PROCESS TO CONTROL UNIFORMITY WHEN  
USING A SELECTIVE SLURRY ON PATTERNED WAFERS**

**ABSTRACT OF THE DISCLOSURE**

- A multistep method of polishing a semiconductor substrate with a
- 5 polishing fluid to remove a selected amount of material from the substrate. In one embodiment the method includes polishing the substrate to remove a first portion of the selected amount of material by holding the substrate against a polishing pad with a polishing force and applying a polishing solution to the polishing pad. Next the polishing pad is rinsed with a rinsing fluid, and afterwards the substrate is further
- 10 polished to remove a second portion of the selected amount of material by holding the substrate against the polishing pad with a polishing force and applying the polishing fluid to the polishing pad.

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